Ming-yue Xiong

List of Publications by Year
in descending order

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		1307594	1474206
9	460	7	9
papers	citations	h-index	g-index

9	9	9	250
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Interface reaction and intermetallic compound growth behavior of Sn-Ag-Cu lead-free solder joints on different substrates in electronic packaging. Journal of Materials Science, 2019, 54, 1741-1768.	3.7	146
2	Reliability issues of lead-free solder joints in electronic devices. Science and Technology of Advanced Materials, 2019, 20, 876-901.	6.1	104
3	Structure and properties of Sn-Cu lead-free solders in electronics packaging. Science and Technology of Advanced Materials, 2019, 20, 421-444.	6.1	83
4	Effect of CuZnAl particles addition on microstructure of Cu/Sn58Bi/Cu TLP bonding solder joints. Vacuum, 2019, 167, 301-306.	3.5	54
5	Influences of doping Ti nanoparticles on microstructure and properties of Sn58Bi solder. Journal of Materials Science: Materials in Electronics, 2019, 30, 17583-17590.	2.2	23
6	Stress analysis and structural optimization of 3-D IC package based on the Taguchi method. Soldering and Surface Mount Technology, 2019, 32, 42-47.	1.5	22
7	Microstructures and properties of SnAgCu lead-free solders bearing CuZnAl particles. Journal of Materials Science: Materials in Electronics, 2019, 30, 15054-15063.	2.2	15
8	Effects of nanoparticles on properties and interface reaction of Sn solder for microelectronic packaging. International Journal of Modern Physics B, 2020, 34, 2050064.	2.0	7
9	The Influence of Carbon Nanotubes on the Properties of Sn Solder. Materials Transactions, 2020, 61, 718-722.	1.2	6